



6L 1+4+1 stackup of board thickness		1.6 mm +/-10%	Thicknes s(mil)	Thicknes s(mm)
		Solder mask	1	0.0254
L1		copper foil + plated	1.6	0.0406
		Prepreg 1080x1	2.8	0.0711
L2		copper foil + plated	1.3	0.0330
		Prepreg 1080x2	6.2	0.1575
L3		copper foil 0.5 oz	0.6	0.0152
	PTH 1-6	CORE	35	0.8890
L4		copper foil 0.5 oz	0.6	0.0152
	PTH 2-5	Prepreg 1080x2	6.2	0.1575
L5		copper foil + plated	1.3	0.0330
		Prepreg 1080x1	2.8	0.0711
L6		copper foil + plated	1.6	0.0406
		Solder mask	1	0.0254
Total:			62	1.5748

Notes:  
All dielectric layer thickness are estimated based on inner layer copper remain ratio 70%  
Mid Tg and Halogen Free material and propose to use TU-747HF

layer	Reference layer	Type	Impedance control(+/- 10%)	Customer Impedance trace width/space(mil)	Customer Impedance trace width/space(mm)	Impedance trace width/space(mil)	Impedance trace width/space(mm)	Evaluated Impedance (ohm)
L1	L2	Differential	90ohm	5.0/12.0	0.127 / 0.3048			
L1	L3	Single	50ohm	19.5	0.4950			
L2	L1/L3	Single	50ohm	3.2	0.0810	3.20		49.2
L2	L1/L3	Differential	90ohm	3.7/9.3	0.094 / 0.236	3.7/9.3		90
L4	L3/L5	Single	50ohm	8.3	0.211			
L4	L3/L5	Differential	90ohm	11/22	0.28/0.56			
L5	L4/L6	Single	50ohm	3.2	0.0810	3.20		49.2
L5	L4/L6	Differential	90ohm	3.7/9.3	0.094 / 0.236	3.7/9.3		90
L6	L4	Single	50ohm	19.5	0.4950			